

# Wafer Specification

## Chip / Product Specific Issue

### for unsawn / sawn Wafer

#### **SLE 66R35**, Version 2.0, 05/2021

This document is valid only in combination with the latest version of the general issue of the chip delivery specification for wafer.

No: V66910-A0638-G001-\*-76

#### Changes in comparison with previous edition:

Date	Version	Change Reason	Change Description
03.2011	1	Possible Systems	Added
10.05.2021	2	Classification	Change document classification

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## 1. **Chip Dimensions**

Location	lot no	type	
Dresden	ZA....	A	stepping size: 0.98 mm x 1.14 mm scribe line: 92 µm / 62 µm Scribe line without searling: according to attached chip layout

## 2. **Possible Systems on the Wafer**

Location	lot no	type	possible systems
Dresden	ZA...	A	25,158

## 3. **Pad Metalization on Front**

Location	lot no	type	
Dresden	ZA...	A	material: AlCu thickness: 600 nm ± 50 nm

## 4. **Passivation**

location	lot no	type	
Dresden	ZA...	A	material: thickness: Plasmaoxide/Plasmanitride 640 nm ± 60 nm Photoimide 2.5 µm ± 0.5 µm

## 5. **Bonding Area (Pad)**

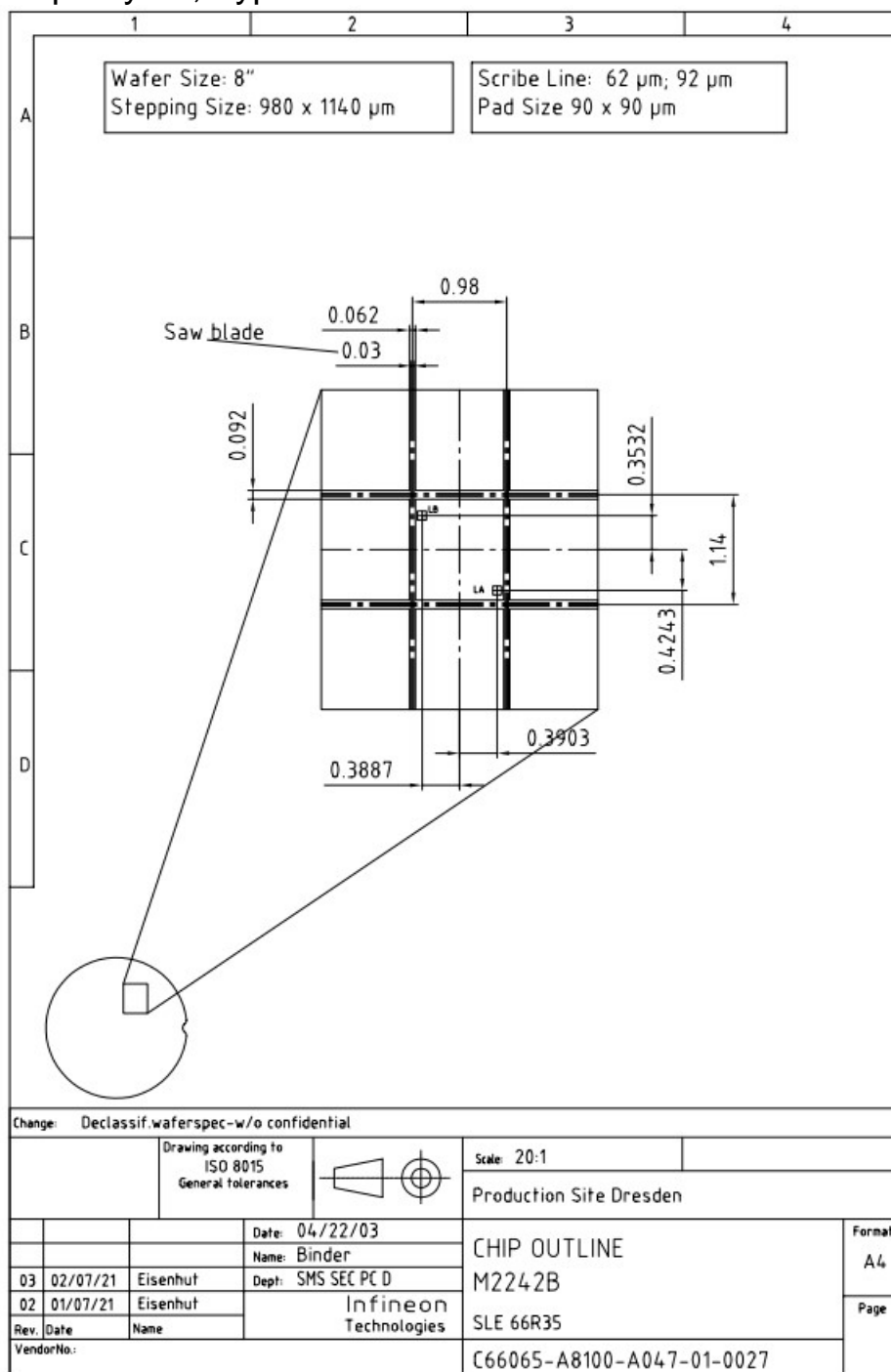
pad size: see Chip Layout, annex a  
bond pad material: depends on respective technology, see 3.  
*recommended condition for die and wire bonding climate:*  
23° C ± 1K, 30 – 60 % rel. humidity

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## Chip Layout, Type A

annex a



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